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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	EE PLD
Delay Time tpd(1) Max	12 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	8
Number of Macrocells	128
Number of Gates	2500
Number of I/O	68
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	84-LCC (J-Lead)
Supplier Device Package	84-PLCC (29.31x29.31)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7128elc84-12

- Additional design entry and simulation support provided by EDIF 2.0.0 and 3.0.0 netlist files, library of parameterized modules (LPM), Verilog HDL, VHDL, and other interfaces to popular EDA tools from manufacturers such as Cadence, Exemplar Logic, Mentor Graphics, OrCAD, Synopsys, and VeriBest
- Programming support
 - Altera's Master Programming Unit (MPU) and programming hardware from third-party manufacturers program all MAX 7000 devices
 - The BitBlaster™ serial download cable, ByteBlasterMV™ parallel port download cable, and MasterBlaster™ serial/universal serial bus (USB) download cable program MAX 7000S devices

General Description

The MAX 7000 family of high-density, high-performance PLDs is based on Altera's second-generation MAX architecture. Fabricated with advanced CMOS technology, the EEPROM-based MAX 7000 family provides 600 to 5,000 usable gates, ISP, pin-to-pin delays as fast as 5 ns, and counter speeds of up to 175.4 MHz. MAX 7000S devices in the -5, -6, -7, and -10 speed grades as well as MAX 7000 and MAX 7000E devices in -5, -6, -7, -10P, and -12P speed grades comply with the PCI Special Interest Group (PCI SIG) *PCI Local Bus Specification, Revision 2.2*. See [Table 3](#) for available speed grades.

Table 3. MAX 7000 Speed Grades

Device	Speed Grade									
	-5	-6	-7	-10P	-10	-12P	-12	-15	-15T	-20
EPM7032		✓	✓		✓		✓	✓	✓	
EPM7032S	✓	✓	✓		✓					
EPM7064		✓	✓		✓		✓	✓		
EPM7064S	✓	✓	✓		✓					
EPM7096			✓		✓		✓	✓		
EPM7128E			✓	✓	✓		✓	✓		✓
EPM7128S		✓	✓		✓			✓		
EPM7160E				✓	✓		✓	✓		✓
EPM7160S		✓	✓		✓			✓		
EPM7192E						✓	✓	✓		✓
EPM7192S			✓		✓			✓		
EPM7256E						✓	✓	✓		✓
EPM7256S			✓		✓			✓		

The MAX 7000E devices—including the EPM7128E, EPM7160E, EPM7192E, and EPM7256E devices—have several enhanced features: additional global clocking, additional output enable controls, enhanced interconnect resources, fast input registers, and a programmable slew rate.

In-system programmable MAX 7000 devices—called MAX 7000S devices—include the EPM7032S, EPM7064S, EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices. MAX 7000S devices have the enhanced features of MAX 7000E devices as well as JTAG BST circuitry in devices with 128 or more macrocells, ISP, and an open-drain output option. See [Table 4](#).

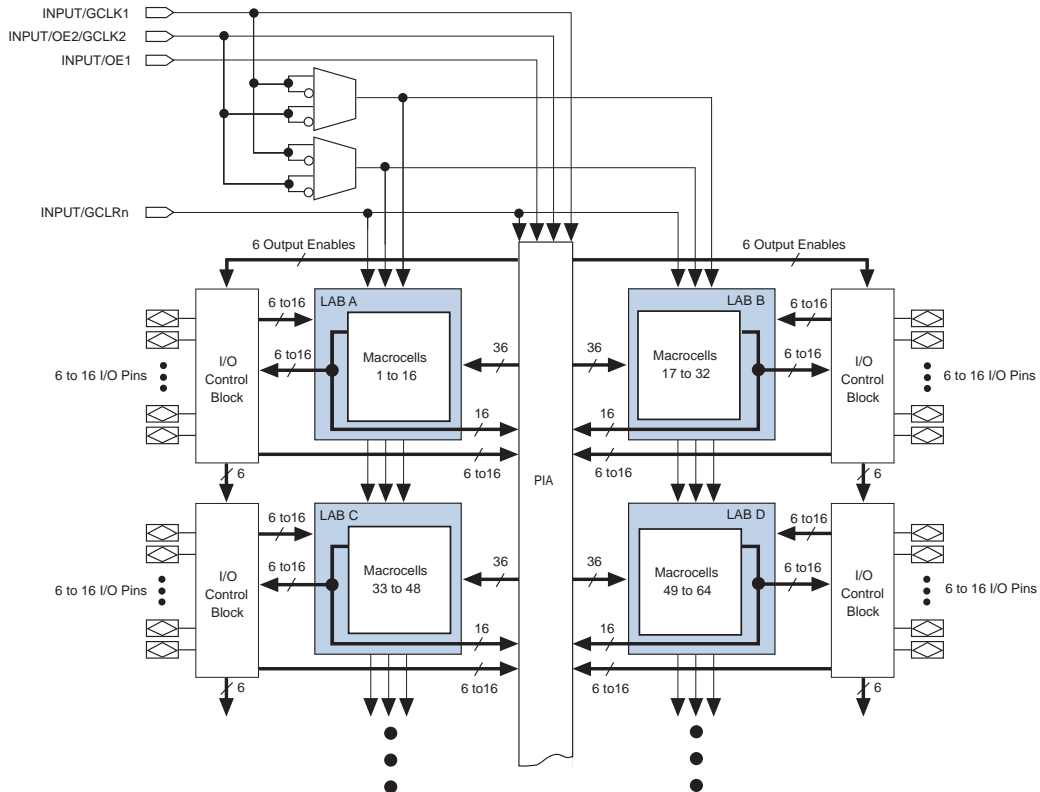
Table 4. MAX 7000 Device Features			
Feature	EPM7032 EPM7064 EPM7096	All MAX 7000E Devices	All MAX 7000S Devices
ISP via JTAG interface			✓
JTAG BST circuitry			✓ ⁽¹⁾
Open-drain output option			✓
Fast input registers		✓	✓
Six global output enables		✓	✓
Two global clocks		✓	✓
Slew-rate control		✓	✓
MultiVolt interface ⁽²⁾	✓	✓	✓
Programmable register	✓	✓	✓
Parallel expanders	✓	✓	✓
Shared expanders	✓	✓	✓
Power-saving mode	✓	✓	✓
Security bit	✓	✓	✓
PCI-compliant devices available	✓	✓	✓

Notes:

- (1) Available only in EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices only.
- (2) The MultiVolt I/O interface is not available in 44-pin packages.

Figure 2 shows the architecture of MAX 7000E and MAX 7000S devices.

Figure 2. MAX 7000E & MAX 7000S Device Block Diagram



Logic Array Blocks

The MAX 7000 device architecture is based on the linking of high-performance, flexible, logic array modules called logic array blocks (LABs). LABs consist of 16-macrocell arrays, as shown in Figures 1 and 2. Multiple LABs are linked together via the programmable interconnect array (PIA), a global bus that is fed by all dedicated inputs, I/O pins, and macrocells.

Each programmable register can be clocked in three different modes:

- By a global clock signal. This mode achieves the fastest clock-to-output performance.
- By a global clock signal and enabled by an active-high clock enable. This mode provides an enable on each flipflop while still achieving the fast clock-to-output performance of the global clock.
- By an array clock implemented with a product term. In this mode, the flipflop can be clocked by signals from buried macrocells or I/O pins.

In EPM7032, EPM7064, and EPM7096 devices, the global clock signal is available from a dedicated clock pin, GCLK1, as shown in [Figure 1](#). In MAX 7000E and MAX 7000S devices, two global clock signals are available. As shown in [Figure 2](#), these global clock signals can be the true or the complement of either of the global clock pins, GCLK1 or GCLK2.

Each register also supports asynchronous preset and clear functions. As shown in [Figures 3 and 4](#), the product-term select matrix allocates product terms to control these operations. Although the product-term-driven preset and clear of the register are active high, active-low control can be obtained by inverting the signal within the logic array. In addition, each register clear function can be individually driven by the active-low dedicated global clear pin (GCLRn). Upon power-up, each register in the device will be set to a low state.

All MAX 7000E and MAX 7000S I/O pins have a fast input path to a macrocell register. This dedicated path allows a signal to bypass the PIA and combinatorial logic and be driven to an input D flipflop with an extremely fast (2.5 ns) input setup time.

Expander Product Terms

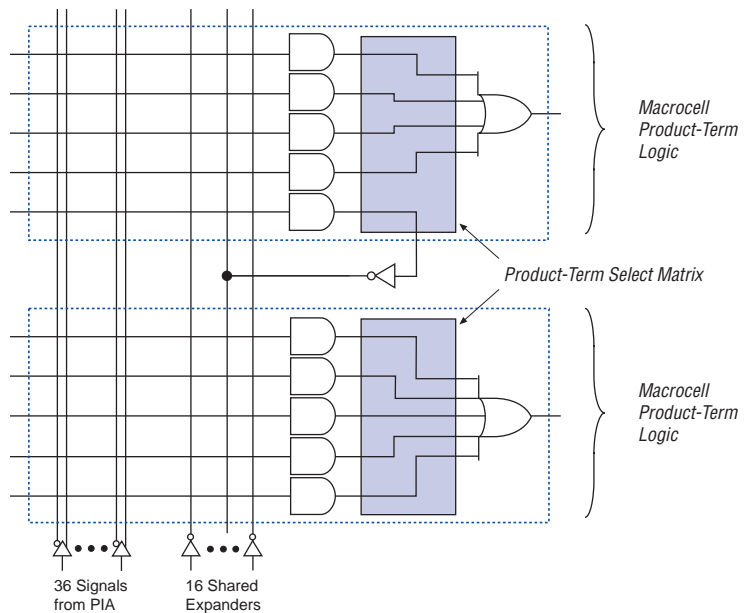
Although most logic functions can be implemented with the five product terms available in each macrocell, the more complex logic functions require additional product terms. Another macrocell can be used to supply the required logic resources; however, the MAX 7000 architecture also allows both shareable and parallel expander product terms (“expanders”) that provide additional product terms directly to any macrocell in the same LAB. These expanders help ensure that logic is synthesized with the fewest possible logic resources to obtain the fastest possible speed.

Shareable Expanders

Each LAB has 16 shareable expanders that can be viewed as a pool of uncommitted single product terms (one from each macrocell) with inverted outputs that feed back into the logic array. Each shareable expander can be used and shared by any or all macrocells in the LAB to build complex logic functions. A small delay (t_{SEXP}) is incurred when shareable expanders are used. Figure 5 shows how shareable expanders can feed multiple macrocells.

Figure 5. Shareable Expanders

Shareable expanders can be shared by any or all macrocells in an LAB.

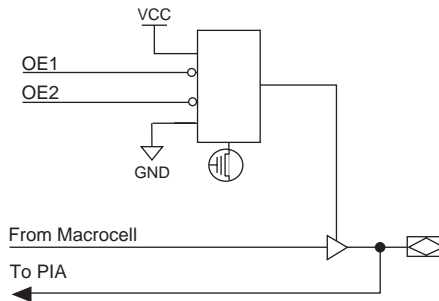


Parallel Expanders

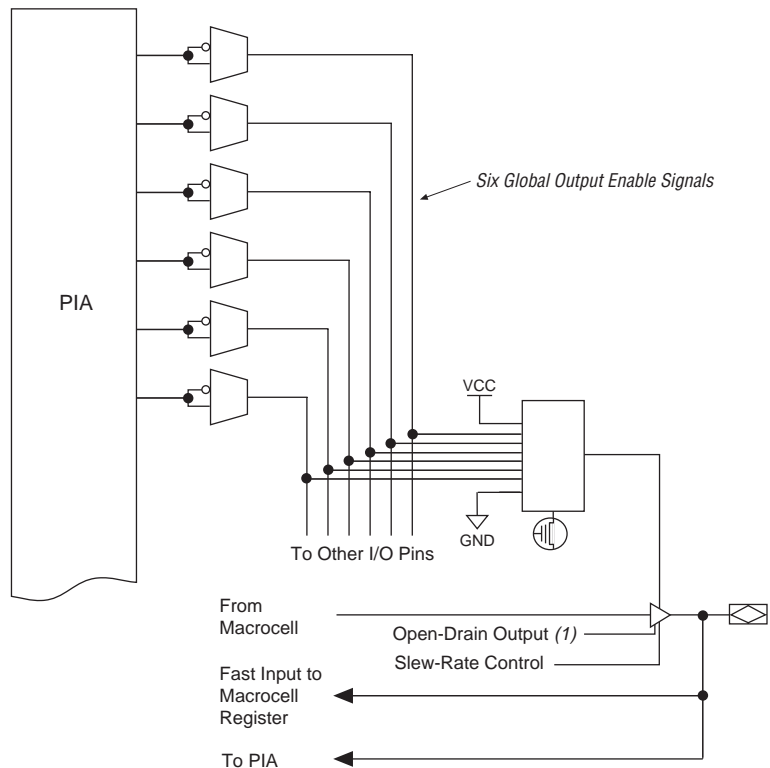
Parallel expanders are unused product terms that can be allocated to a neighboring macrocell to implement fast, complex logic functions. Parallel expanders allow up to 20 product terms to directly feed the macrocell OR logic, with five product terms provided by the macrocell and 15 parallel expanders provided by neighboring macrocells in the LAB.

Figure 8. I/O Control Block of MAX 7000 Devices

EPM7032, EPM7064 & EPM7096 Devices



MAX 7000E & MAX 7000S Devices



Note:

- (1) The open-drain output option is available only in MAX 7000S devices.

The instruction register length of MAX 7000S devices is 10 bits. Tables 10 and 11 show the boundary-scan register length and device IDCODE information for MAX 7000S devices.

Table 10. MAX 7000S Boundary-Scan Register Length

Device	Boundary-Scan Register Length
EPM7032S	1 (1)
EPM7064S	1 (1)
EPM7128S	288
EPM7160S	312
EPM7192S	360
EPM7256S	480

Note:

- (1) This device does not support JTAG boundary-scan testing. Selecting either the EXTEST or SAMPLE/PRELOAD instruction will select the one-bit bypass register.

Table 11. 32-Bit MAX 7000 Device IDCODE Note (1)

Device	IDCODE (32 Bits)			
	Version (4 Bits)	Part Number (16 Bits)	Manufacturer's Identity (11 Bits)	1 (1 Bit) (2)
EPM7032S	0000	0111 0000 0011 0010	00001101110	1
EPM7064S	0000	0111 0000 0110 0100	00001101110	1
EPM7128S	0000	0111 0001 0010 1000	00001101110	1
EPM7160S	0000	0111 0001 0110 0000	00001101110	1
EPM7192S	0000	0111 0001 1001 0010	00001101110	1
EPM7256S	0000	0111 0010 0101 0110	00001101110	1

Notes:

- (1) The most significant bit (MSB) is on the left.
 (2) The least significant bit (LSB) for all JTAG IDCODEs is 1.

Table 15. MAX 7000 5.0-V Device DC Operating Conditions *Note (9)*

Symbol	Parameter	Conditions	Min	Max	Unit
V_{IH}	High-level input voltage		2.0	$V_{CCINT} + 0.5$	V
V_{IL}	Low-level input voltage		-0.5 (8)	0.8	V
V_{OH}	5.0-V high-level TTL output voltage	$I_{OH} = -4$ mA DC, $V_{CCIO} = 4.75$ V (10)	2.4		V
	3.3-V high-level TTL output voltage	$I_{OH} = -4$ mA DC, $V_{CCIO} = 3.00$ V (10)	2.4		V
	3.3-V high-level CMOS output voltage	$I_{OH} = -0.1$ mA DC, $V_{CCIO} = 3.0$ V (10)	$V_{CCIO} - 0.2$		V
V_{OL}	5.0-V low-level TTL output voltage	$I_{OL} = 12$ mA DC, $V_{CCIO} = 4.75$ V (11)		0.45	V
	3.3-V low-level TTL output voltage	$I_{OL} = 12$ mA DC, $V_{CCIO} = 3.00$ V (11)		0.45	V
	3.3-V low-level CMOS output voltage	$I_{OL} = 0.1$ mA DC, $V_{CCIO} = 3.0$ V (11)		0.2	V
I_I	Leakage current of dedicated input pins	$V_I = -0.5$ to 5.5 V (11)	-10	10	μ A
I_{OZ}	I/O pin tri-state output off-state current	$V_I = -0.5$ to 5.5 V (11), (12)	-40	40	μ A

Table 16. MAX 7000 5.0-V Device Capacitance: EPM7032, EPM7064 & EPM7096 Devices *Note (13)*

Symbol	Parameter	Conditions	Min	Max	Unit
C_{IN}	Input pin capacitance	$V_{IN} = 0$ V, $f = 1.0$ MHz		12	pF
$C_{I/O}$	I/O pin capacitance	$V_{OUT} = 0$ V, $f = 1.0$ MHz		12	pF

Table 17. MAX 7000 5.0-V Device Capacitance: MAX 7000E Devices *Note (13)*

Symbol	Parameter	Conditions	Min	Max	Unit
C_{IN}	Input pin capacitance	$V_{IN} = 0$ V, $f = 1.0$ MHz		15	pF
$C_{I/O}$	I/O pin capacitance	$V_{OUT} = 0$ V, $f = 1.0$ MHz		15	pF

Table 18. MAX 7000 5.0-V Device Capacitance: MAX 7000S Devices *Note (13)*

Symbol	Parameter	Conditions	Min	Max	Unit
C_{IN}	Dedicated input pin capacitance	$V_{IN} = 0$ V, $f = 1.0$ MHz		10	pF
$C_{I/O}$	I/O pin capacitance	$V_{OUT} = 0$ V, $f = 1.0$ MHz		10	pF

Table 25. MAX 7000 & MAX 7000E External Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-15		-15T		-20		
			Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		15.0		15.0		20.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		15.0		15.0		20.0	ns
t _{SU}	Global clock setup time		11.0		11.0		12.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input	(2)	3.0		–		5.0		ns
t _{FH}	Global clock hold time of fast input	(2)	0.0		–		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		8.0		8.0		12.0	ns
t _{CH}	Global clock high time		5.0		6.0		6.0		ns
t _{CL}	Global clock low time		5.0		6.0		6.0		ns
t _{ASU}	Array clock setup time		4.0		4.0		5.0		ns
t _{AH}	Array clock hold time		4.0		4.0		5.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		15.0		15.0		20.0	ns
t _{ACH}	Array clock high time		6.0		6.5		8.0		ns
t _{ACL}	Array clock low time		6.0		6.5		8.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(3)	6.0		6.5		8.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			13.0		13.0		16.0	ns
f _{CNT}	Maximum internal global clock frequency	(5)	76.9		76.9		62.5		MHz
t _{ACNT}	Minimum array clock period			13.0		13.0		16.0	ns
f _{ACNT}	Maximum internal array clock frequency	(5)	76.9		76.9		62.5		MHz
f _{MAX}	Maximum clock frequency	(6)	100		83.3		83.3		MHz

Table 26. MAX 7000 & MAX 7000E Internal Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-15		-15T		-20		
			Min	Max	Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			2.0		2.0		3.0	ns
t_{IO}	I/O input pad and buffer delay			2.0		2.0		3.0	ns
t_{FIN}	Fast input delay	(2)		2.0		–		4.0	ns
t_{SEXP}	Shared expander delay			8.0		10.0		9.0	ns
t_{PEXP}	Parallel expander delay			1.0		1.0		2.0	ns
t_{LAD}	Logic array delay			6.0		6.0		8.0	ns
t_{LAC}	Logic control array delay			6.0		6.0		8.0	ns
t_{IOE}	Internal output enable delay	(2)		3.0		–		4.0	ns
t_{OD1}	Output buffer and pad delay Slow slew rate = off $V_{CCIO} = 5.0\text{ V}$	$C1 = 35\text{ pF}$		4.0		4.0		5.0	ns
t_{OD2}	Output buffer and pad delay Slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$ (7)		5.0		–		6.0	ns
t_{OD3}	Output buffer and pad delay Slow slew rate = on $V_{CCIO} = 5.0\text{ V}$ or 3.3 V	$C1 = 35\text{ pF}$ (2)		8.0		–		9.0	ns
t_{ZX1}	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 5.0\text{ V}$	$C1 = 35\text{ pF}$		6.0		6.0		10.0	ns
t_{ZX2}	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$ (7)		7.0		–		11.0	ns
t_{ZX3}	Output buffer enable delay Slow slew rate = on $V_{CCIO} = 5.0\text{ V}$ or 3.3 V	$C1 = 35\text{ pF}$ (2)		10.0		–		14.0	ns
t_{XZ}	Output buffer disable delay	$C1 = 5\text{ pF}$		6.0		6.0		10.0	ns
t_{SU}	Register setup time		4.0		4.0		4.0		ns
t_H	Register hold time		4.0		4.0		5.0		ns
t_{FSU}	Register setup time of fast input	(2)	2.0		–		4.0		ns
t_{FH}	Register hold time of fast input	(2)	2.0		–		3.0		ns
t_{RD}	Register delay			1.0		1.0		1.0	ns
t_{COMB}	Combinatorial delay			1.0		1.0		1.0	ns
t_{IC}	Array clock delay			6.0		6.0		8.0	ns
t_{EN}	Register enable time			6.0		6.0		8.0	ns
t_{GLOB}	Global control delay			1.0		1.0		3.0	ns
t_{PRE}	Register preset time			4.0		4.0		4.0	ns
t_{CLR}	Register clear time			4.0		4.0		4.0	ns
t_{PIA}	PIA delay			2.0		2.0		3.0	ns
t_{LPA}	Low-power adder	(8)		13.0		15.0		15.0	ns

Table 28. EPM7032S Internal Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{PIA}	PIA delay	(7)		1.1		1.1		1.4		1.0	ns
t_{LPA}	Low-power adder	(8)		12.0		10.0		10.0		11.0	ns

Notes to tables:

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3\text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 29 and 30 show the EPM7064S AC operating conditions.

Table 29. EPM7064S External Timing Parameters (Part 1 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t _{SU}	Global clock setup time		2.9		3.6		6.0		7.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		2.5		3.0		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.5		0.5		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		3.2		4.0		4.5		5.0	ns
t _{CH}	Global clock high time		2.0		2.5		3.0		4.0		ns
t _{CL}	Global clock low time		2.0		2.5		3.0		4.0		ns
t _{ASU}	Array clock setup time		0.7		0.9		3.0		2.0		ns
t _{AH}	Array clock hold time		1.8		2.1		2.0		3.0		ns

Tables 31 and 32 show the EPM7128S AC operating conditions.

Table 31. EPM7128S External Timing Parameters Note (1)											
Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t _{SU}	Global clock setup time		3.4		6.0		7.0		11.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.5		0.5		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		4.0		4.5		5.0		8.0	ns
t _{CH}	Global clock high time		3.0		3.0		4.0		5.0		ns
t _{CL}	Global clock low time		3.0		3.0		4.0		5.0		ns
t _{ASU}	Array clock setup time		0.9		3.0		2.0		4.0		ns
t _{AH}	Array clock hold time		1.8		2.0		5.0		4.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		6.5		7.5		10.0		15.0	ns
t _{ACH}	Array clock high time		3.0		3.0		4.0		6.0		ns
t _{ACL}	Array clock low time		3.0		3.0		4.0		6.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(2)	3.0		3.0		4.0		6.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			6.8		8.0		10.0		13.0	ns
f _{CNT}	Maximum internal global clock frequency	(4)	147.1		125.0		100.0		76.9		MHz
t _{ACNT}	Minimum array clock period			6.8		8.0		10.0		13.0	ns
f _{ACNT}	Maximum internal array clock frequency	(4)	147.1		125.0		100.0		76.9		MHz
f _{MAX}	Maximum clock frequency	(5)	166.7		166.7		125.0		100.0		MHz

Table 33. EPM7160S External Timing Parameters (Part 2 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{ACNT}	Minimum array clock period			6.7		8.2		10.0		13.0	ns
f _{ACNT}	Maximum internal array clock frequency	(4)	149.3		122.0		100.0		76.9		MHz
f _{MAX}	Maximum clock frequency	(5)	166.7		166.7		125.0		100.0		MHz

Table 34. EPM7160S Internal Timing Parameters (Part 1 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			0.2		0.3		0.5		2.0	ns
t_{IO}	I/O input pad and buffer delay			0.2		0.3		0.5		2.0	ns
t_{FIN}	Fast input delay			2.6		3.2		1.0		2.0	ns
t_{SEXP}	Shared expander delay			3.6		4.3		5.0		8.0	ns
t_{PEXP}	Parallel expander delay			1.0		1.3		0.8		1.0	ns
t_{LAD}	Logic array delay			2.8		3.4		5.0		6.0	ns
t_{LAC}	Logic control array delay			2.8		3.4		5.0		6.0	ns
t_{IOE}	Internal output enable delay			0.7		0.9		2.0		3.0	ns
t_{OD1}	Output buffer and pad delay	C1 = 35 pF		0.4		0.5		1.5		4.0	ns
t_{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		0.9		1.0		2.0		5.0	ns
t_{OD3}	Output buffer and pad delay	C1 = 35 pF		5.4		5.5		5.5		8.0	ns
t_{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		4.0		5.0		6.0	ns
t_{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		5.5		7.0	ns
t_{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		10.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		5.0		6.0	ns
t_{SU}	Register setup time		1.0		1.2		2.0		4.0		ns
t_H	Register hold time		1.6		2.0		3.0		4.0		ns
t_{FSU}	Register setup time of fast input		1.9		2.2		3.0		2.0		ns
t_{FH}	Register hold time of fast input		0.6		0.8		0.5		1.0		ns
t_{RD}	Register delay			1.3		1.6		2.0		1.0	ns
t_{COMB}	Combinatorial delay			1.0		1.3		2.0		1.0	ns
t_{IC}	Array clock delay			2.9		3.5		5.0		6.0	ns
t_{EN}	Register enable time			2.8		3.4		5.0		6.0	ns
t_{GLOB}	Global control delay			2.0		2.4		1.0		1.0	ns
t_{PRE}	Register preset time			2.4		3.0		3.0		4.0	ns

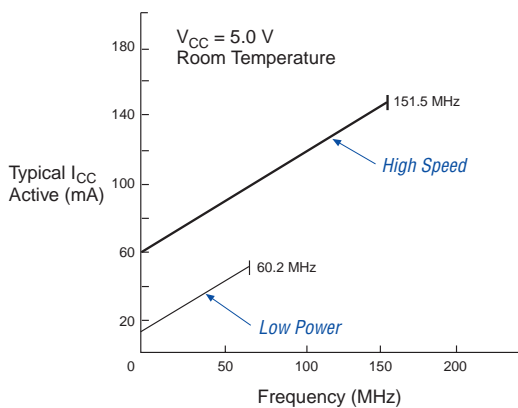
Table 38. EPM7256S Internal Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-15		
			Min	Max	Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			0.3		0.5		2.0	ns
t_{IO}	I/O input pad and buffer delay			0.3		0.5		2.0	ns
t_{FIN}	Fast input delay			3.4		1.0		2.0	ns
t_{SEXP}	Shared expander delay			3.9		5.0		8.0	ns
t_{PEXP}	Parallel expander delay			1.1		0.8		1.0	ns
t_{LAD}	Logic array delay			2.6		5.0		6.0	ns
t_{LAC}	Logic control array delay			2.6		5.0		6.0	ns
t_{IOE}	Internal output enable delay			0.8		2.0		3.0	ns
t_{OD1}	Output buffer and pad delay	C1 = 35 pF		0.5		1.5		4.0	ns
t_{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		1.0		2.0		5.0	ns
t_{OD3}	Output buffer and pad delay	C1 = 35 pF		5.5		5.5		8.0	ns
t_{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		5.0		6.0	ns
t_{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		5.5		7.0	ns
t_{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		10.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		5.0		6.0	ns
t_{SU}	Register setup time		1.1		2.0		4.0		ns
t_H	Register hold time		1.6		3.0		4.0		ns
t_{FSU}	Register setup time of fast input		2.4		3.0		2.0		ns
t_{FH}	Register hold time of fast input		0.6		0.5		1.0		ns
t_{RD}	Register delay			1.1		2.0		1.0	ns
t_{COMB}	Combinatorial delay			1.1		2.0		1.0	ns
t_{IC}	Array clock delay			2.9		5.0		6.0	ns
t_{EN}	Register enable time			2.6		5.0		6.0	ns
t_{GLOB}	Global control delay			2.8		1.0		1.0	ns
t_{PRE}	Register preset time			2.7		3.0		4.0	ns
t_{CLR}	Register clear time			2.7		3.0		4.0	ns
t_{PIA}	PIA delay	(7)		3.0		1.0		2.0	ns
t_{LPA}	Low-power adder	(8)		10.0		11.0		13.0	ns

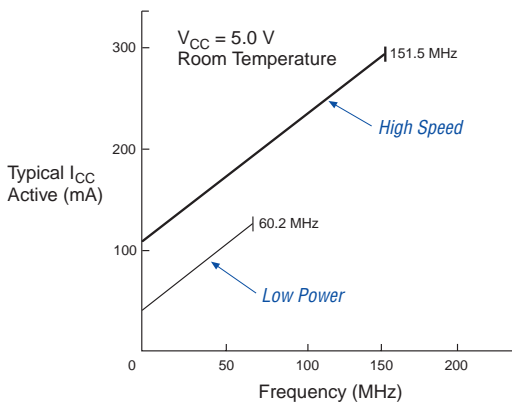
Figure 14 shows typical supply current versus frequency for MAX 7000 devices.

Figure 14. I_{CC} vs. Frequency for MAX 7000 Devices (Part 1 of 2)

EPM7032



EPM7064



EPM7096

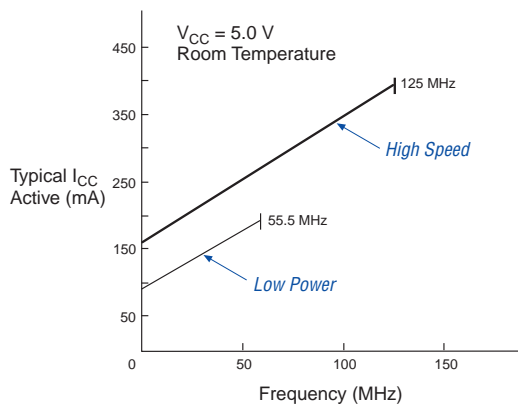
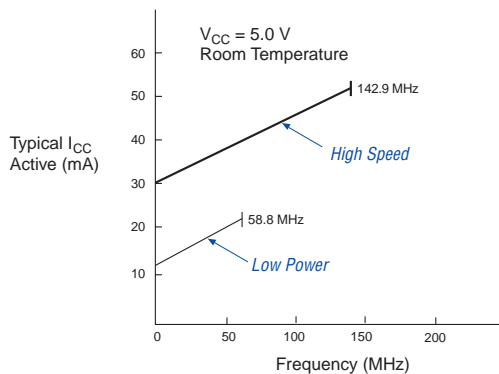


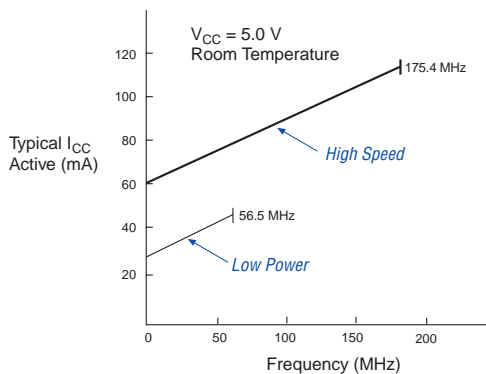
Figure 15 shows typical supply current versus frequency for MAX 7000S devices.

Figure 15. I_{CC} vs. Frequency for MAX 7000S Devices (Part 1 of 2)

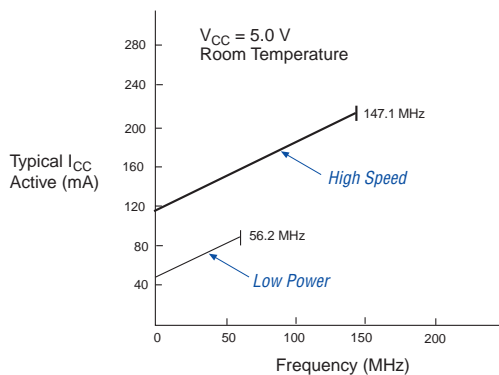
EPM7032S



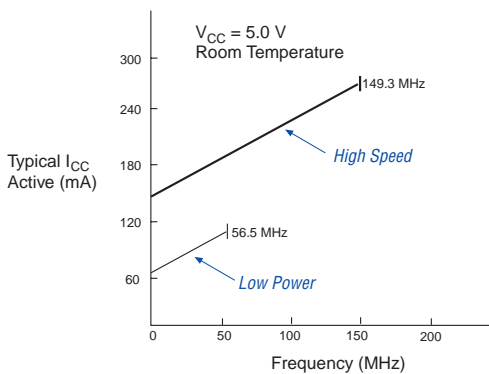
EPM7064S



EPM7128S



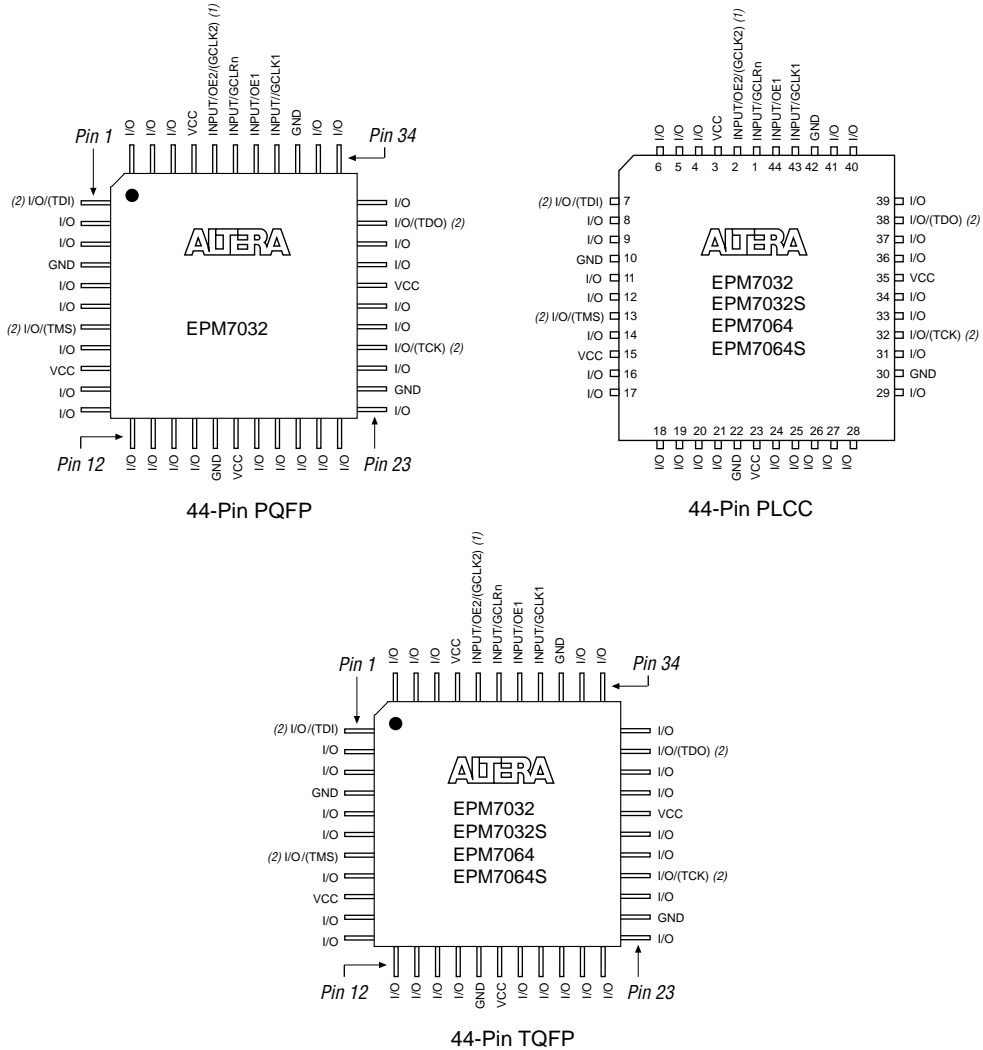
EPM7160S



Figures 16 through 22 show the package pin-out diagrams for MAX 7000 devices.

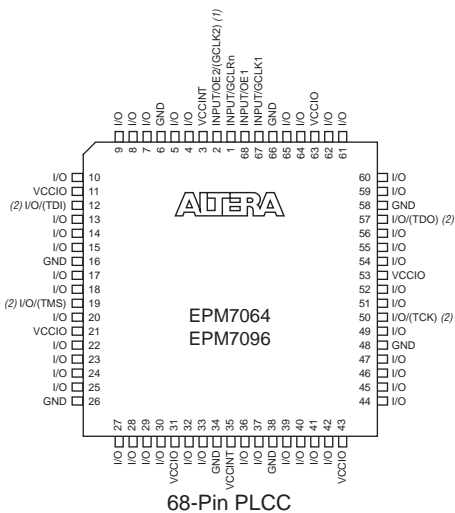
Figure 16. 44-Pin Package Pin-Out Diagram

Package outlines not drawn to scale.



Notes:

- (1) The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
- (2) JTAG ports are available in MAX 7000S devices only.

Figure 17. 68-Pin Package Pin-Out Diagram*Package outlines not drawn to scale.***Notes:**

- (1) The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
- (2) JTAG ports are available in MAX 7000S devices only.



Notes:



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